

46-624 Economy Version

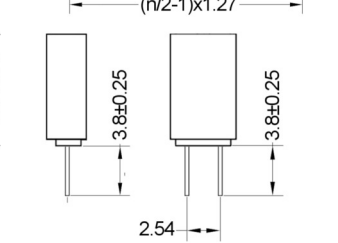
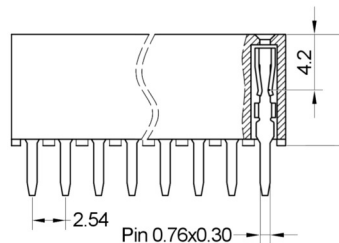
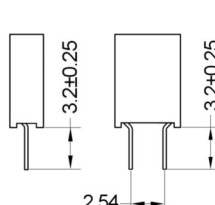
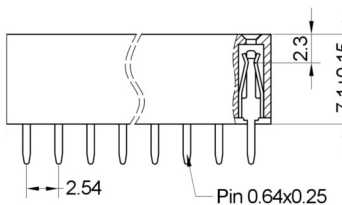
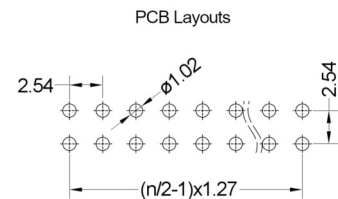
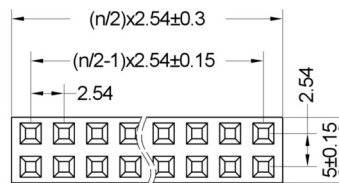
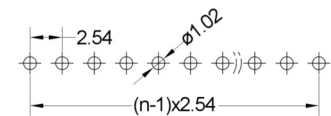
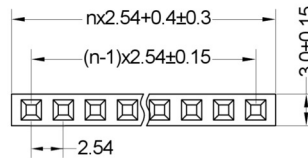
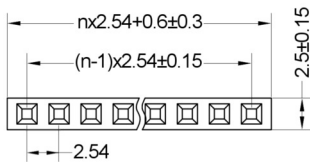
Buchsenleisten RM 2,54mm, gerade, 1-/2-reihig – BH 7,1/8,5mm
 Female Headers, 2.54mm Pitch, Straight, Single/Double Row – 7.1/8.5mm Profile

Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ < 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ > 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	1000 V AC/DC 1000 V AC/DC
Nennstrom <i>Current Rating</i>	3 A 3 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +105 °C -40 °C ... +105 °C
Verarbeitung <i>Processing</i>	230 °C für 30-60 Sekunden (260 °C für 10 Sekunden) 230 °C for 30-60 seconds (260 °C for 10 seconds)



Doppelfederkontakte für
 Vierkantstifte 0,635mm.
*Dual beam contacts accept
 0.635mm square pins.*



Series

46-624

Contacts*

28

02-40 Einreihig
Single row
 04-80 Zweireihig
Double row

Rows*

1

1 Einreihig
Single row
 2 Zweireihig
Double row

Type*

10

10 Bauhöhe 7.10mm
Height 7.10mm
 20 Bauhöhe 8.50mm
Height 8.50mm

Plating

00

00 Vergoldet
Gold plated

* Dies ist ein **Bestellbeispiel** -
 bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** -
 please replace by your specifications.

Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

